



Click [here](#) for the 3D model.

Dimensions

| | |
|-----------|--|
| Chip Size | 1825 |
| L | 4.572mm +/-0.381mm (0.18 in +/-0.015 in) |
| W | 6.35mm +/-0.381mm (0.25 in +/-0.015 in) |
| T | 2.032mm MAX (0.08 in MAX) |

Packaging Specifications

| | |
|--------------------|--------|
| Packaging | Waffle |
| Packaging Quantity | 25000 |

General Information

| | |
|--------------|--|
| Series | SMD Mil PRF123 |
| Style | SMD Chip |
| Description | SMD Chip, Temperature Stable |
| RoHS | No |
| Prop 65 | ⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov |
| Termination | Tin |
| Failure Rate | N/A |
| AEC-Q200 | No |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Specifications

| | |
|--|---------------------|
| Capacitance | 0.082 uF |
| Capacitance Tolerance | 10% |
| Voltage DC | 100 VDC |
| Dielectric Withstanding Voltage | 250 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | BX |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1kHz 1.0Vms |
| Dissipation Factor | 2.5% |
| Insulation Resistance | 100 GOhms |

单击下面可查看定价，库存，交付和生命周期等信息

[>>KEMET\(基美\)](#)